



## Material Content Data Sheet



<b>Sales Product Name</b>		IPA60R199CP		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000911414							
<b>Package</b>		PG-TO220-3-253		<b>Weight*</b>		2135.57 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.809	0.41	0.41	4125	4125	
leadframe	non noble metal	iron	7439-89-6	1.431	0.07		670		
	inorganic material	phosphorus	7723-14-0	0.429	0.02		201		
	non noble metal	copper	7440-50-8	1428.770	66.90	66.99	669035	669906	
wire	non noble metal	aluminium	7429-90-5	2.991	0.14	0.14	1400	1400	
encapsulation	organic material	carbon black	1333-86-4	3.329	0.16		1559		
	plastics	epoxy resin	-	129.815	6.08		60787		
	inorganic material	silicondioxide	60676-86-0	532.573	24.94	31.18	249382	311728	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.00	1.00	10050	10050	
plating	non noble metal	nickel	7440-02-0	1.764	0.08	0.08	826	826	
solder	non noble metal	antimony	7440-36-0	0.420	0.02		197		
	noble metal	silver	7440-22-4	1.049	0.05		491		
	non noble metal	tin	7440-31-5	2.728	0.13	0.20	1277	1965	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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